

Analog Semiconductor Leaders' Forum

Dongbu HiTek's Analog Manufacturing Competitiveness

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Introduction

Dongbu HiTek Manufacturing Division

- **One of the Top 5 Semiconductor foundries in the world.**
- **Leading Analog/Mixed Signal foundry founded in 1997.**
- **Generated \$250M revenue in 1H 2010.**
- **2 world class 200mm fabs with capacity of 94K WSPM.**
- **Certified for QS9000/9001, TS16949, ISO27001.**
- **Talented and dedicated HR with TPM and 6 Sigma.**

Fab Facilities

- *Fab1 in Bucheon producing state of the art chips across 0.15-0.35u*
- *Fab2 in Eumsung producing cutting edge solutions across 90nm-0.25u*

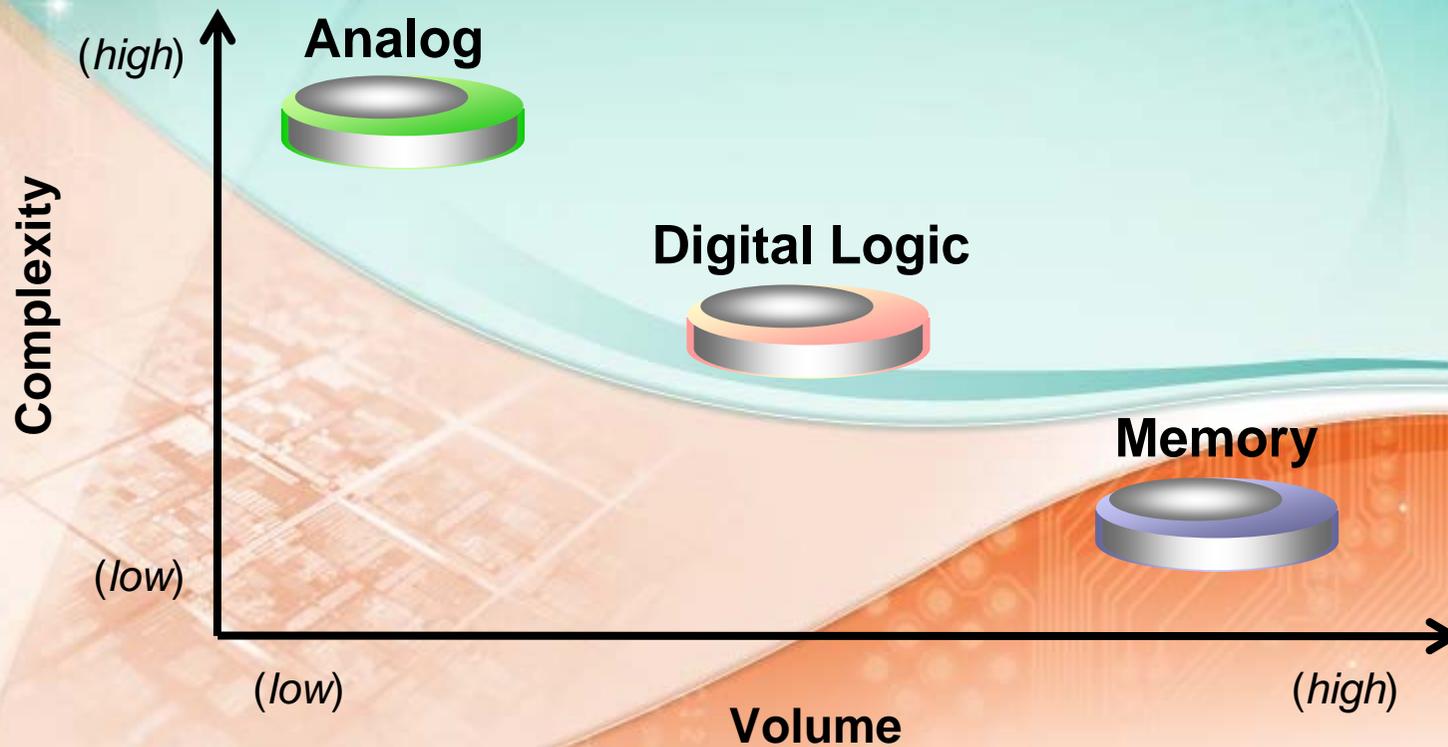


Fab 1	
Capacity	52,000 wafers/month
Tech Nodes	0.35, 0.25, 0.18, 0.15um
Main Technology	BCDMOS, Analog CMOS and HV CMOS, Logic
Wafer Size	200mm (8 inch)
Location	Bucheon, Gyunggi-do

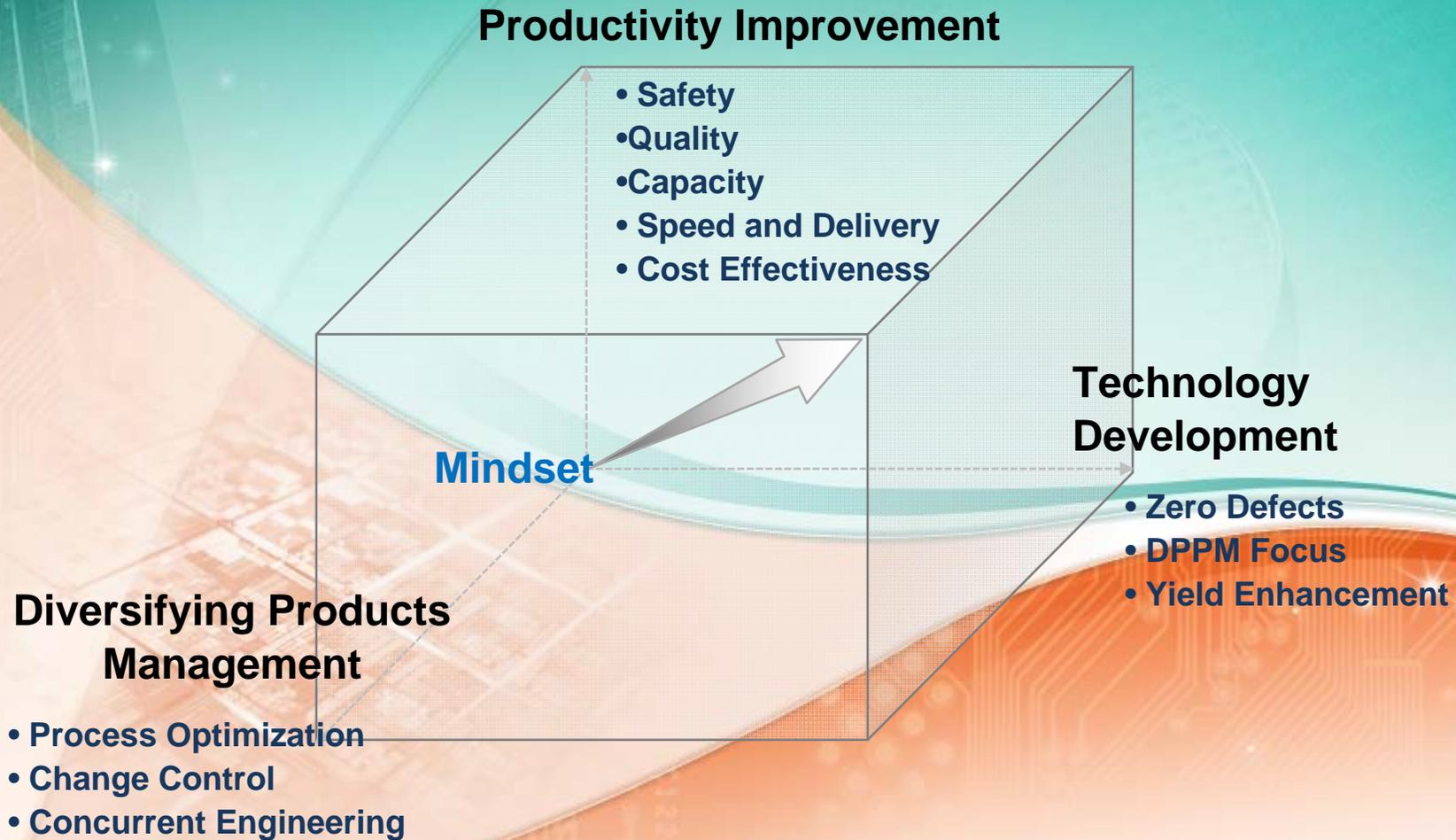
Fab 2	
Capacity	42,000 wafers/month
Tech Nodes	0.25, 0.18, 0.13, 0.11, 0.09um
Main Technology	Mixed Signal, Flash, RF CMOS, CIS and HV CMOS, Logic
Wafer Size	200mm (8 inch)
Location	Eumsung, Choong Chung Book-do

Analog Manufacturing Model

- *High complexity with low volume business*



The Key Factors of Analog Manufacturing



Analog Management Mindset

➤ **Silicon Accuracy**

- Rich Component Set
- Tight Parametric Distributions
- Exhaustive Device Characterization

➤ **Simulation Accuracy**

- Thorough PDK “That Works “
- SPICE Models That Match Silicon
- Proven IP Blocks for Key Functions

➤ **Manufacturability**

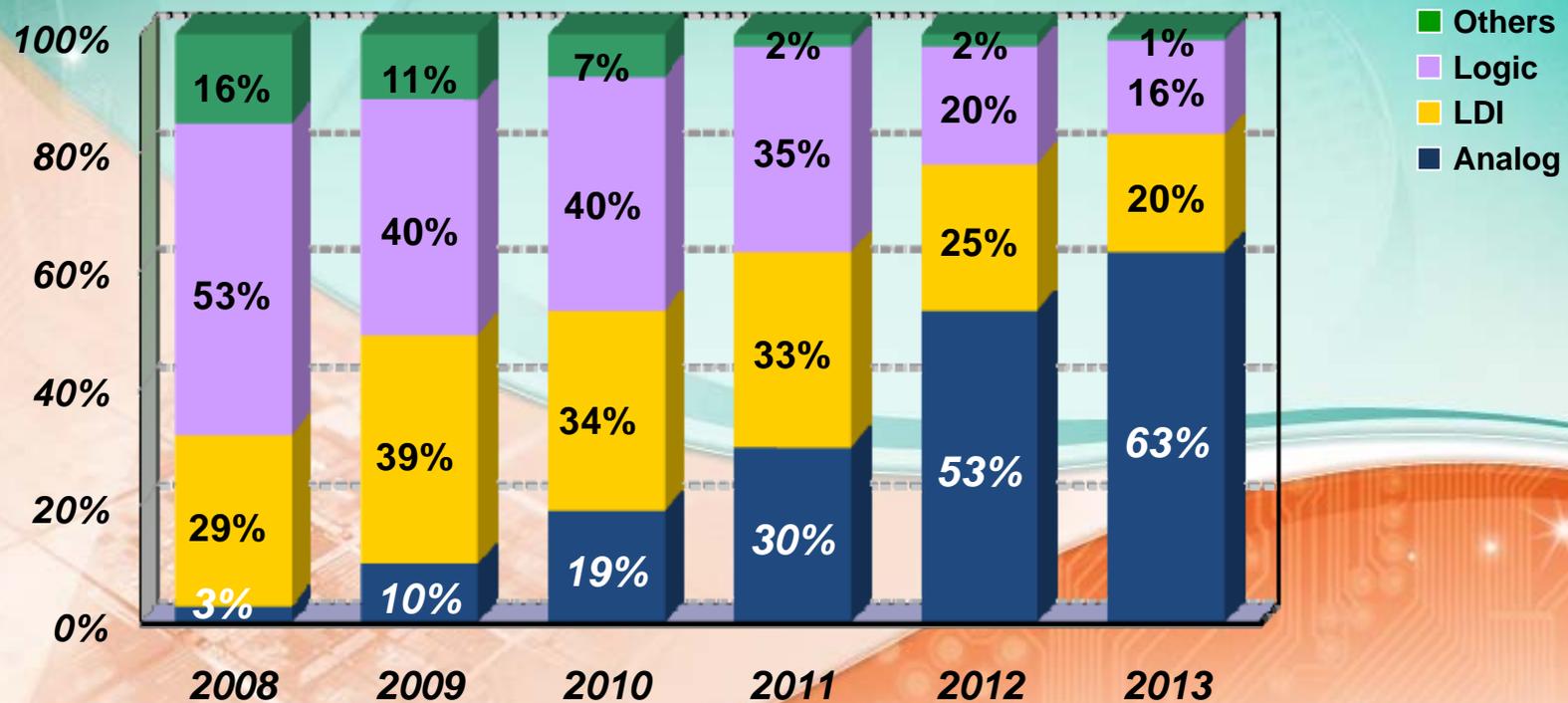
- Advanced Statistical Factory Control
- Zero Defects, DPPM Focus
- Yield Enhancement
- Fast, Consistent and Predictable

Manufacturing Services and Support

- **Small volume product focus, too.**
- **Fast cycle times for prototypes and production.**
- **On time delivery.**
- **Demonstrated manufacturability.**
- **Responsiveness and willingness to be flexible.**

Trend (1) Total Output Breakdown

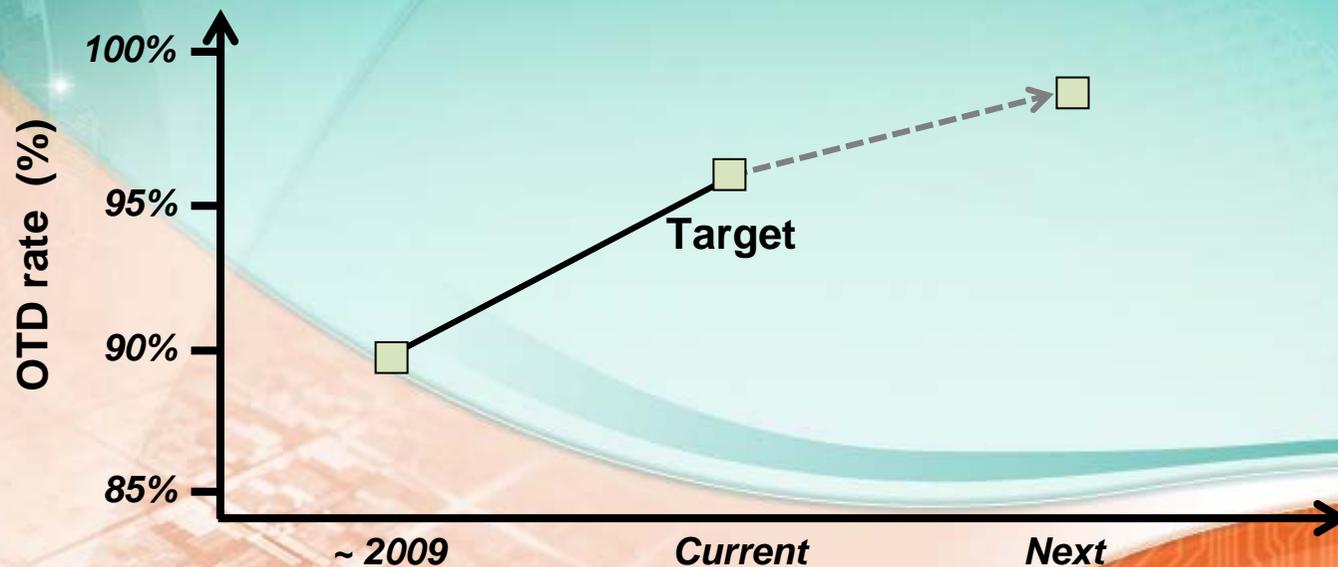
- *Continuous Analog business growth*



Source : Dongbu HiTek Internal estimation (for Bucheon Fab)

Trend (2) On Time Delivery

- **Criticality of time to market focus**



- **Productivity improvement for the bottleneck process.**
- **Process streamline and dedication free for flexible process**
- **Automated scheduling and processing based on 'Pull paradigm'**
- **Customized components sets based on advanced 'Backbone process'**

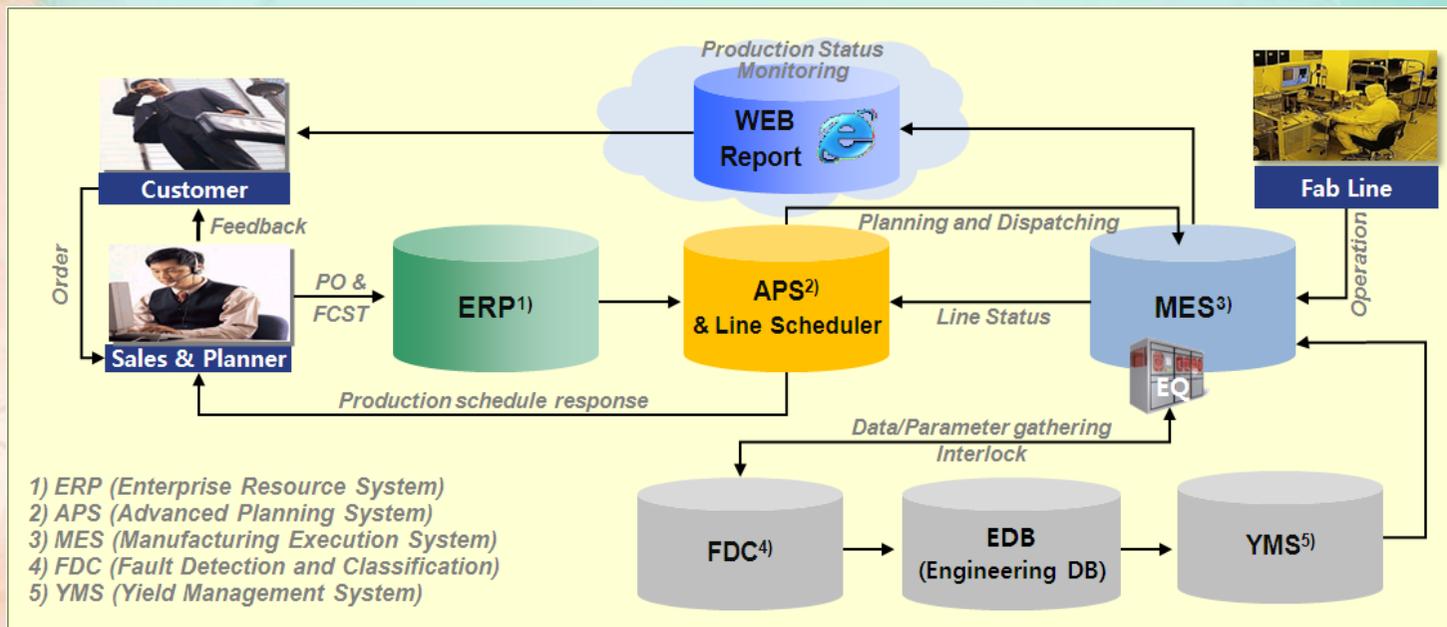
Manufacturing Infrastructure

➤ Advanced and Computerized Fab

for highly optimized management on complexity, utilization and SPC.

➤ Sophisticated Scheduling

for improving cycle time and on-time delivery.

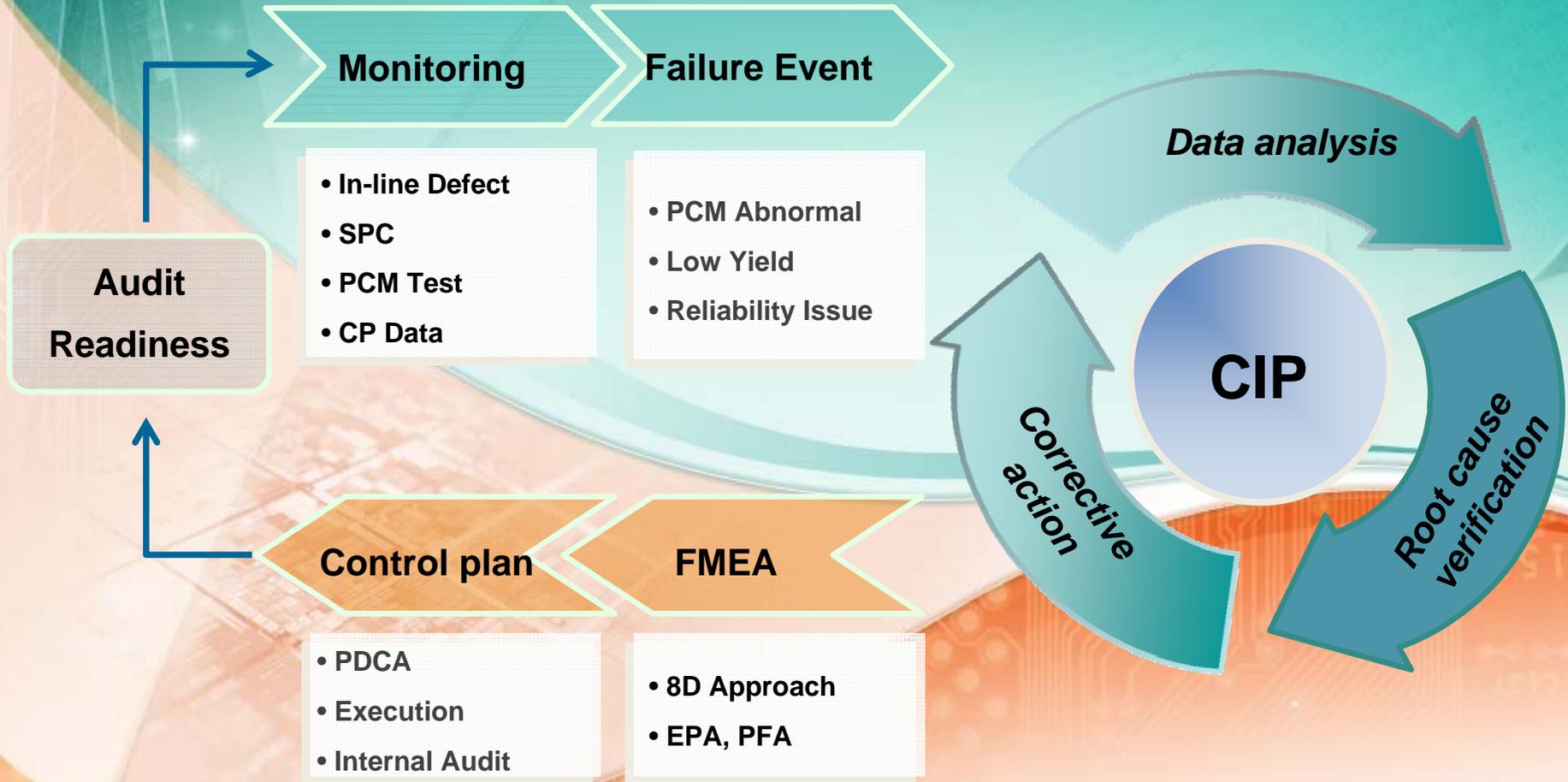


- Planning and dispatching for complex manufacturing flows
- Real time SPC and early quality management

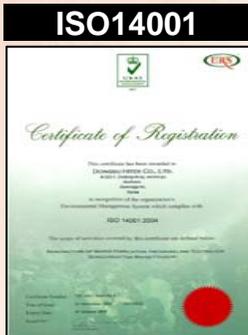
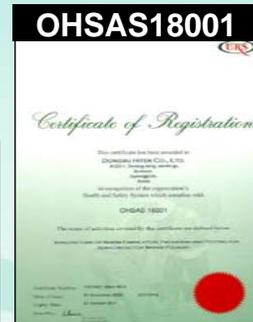
Quality Mindset

- **Zero defects and DPPM performance.**
- **Inline defect monitoring and process control.**
- **Tight and predictable parametric performance.**
- **Yield maximizing techniques.**
- **Rigorous product qualification.**
- **Long term reliability.**

Integrated Quality Management System



Quality Assurance Certification



Information Security

- ISO27001 (Oct.02, 2006, BSI / UKAS)
- **Green Partner Environmental System**
- Sony G-partner (Jun.12, 2006, Sony)
- Samsung S-partner (Mar.04, 2009, Samsung)

Occupational Health & Safety Management System

- OHSAS18001 (Nov.03, 2004, URS / UKAS)

Quality Management System

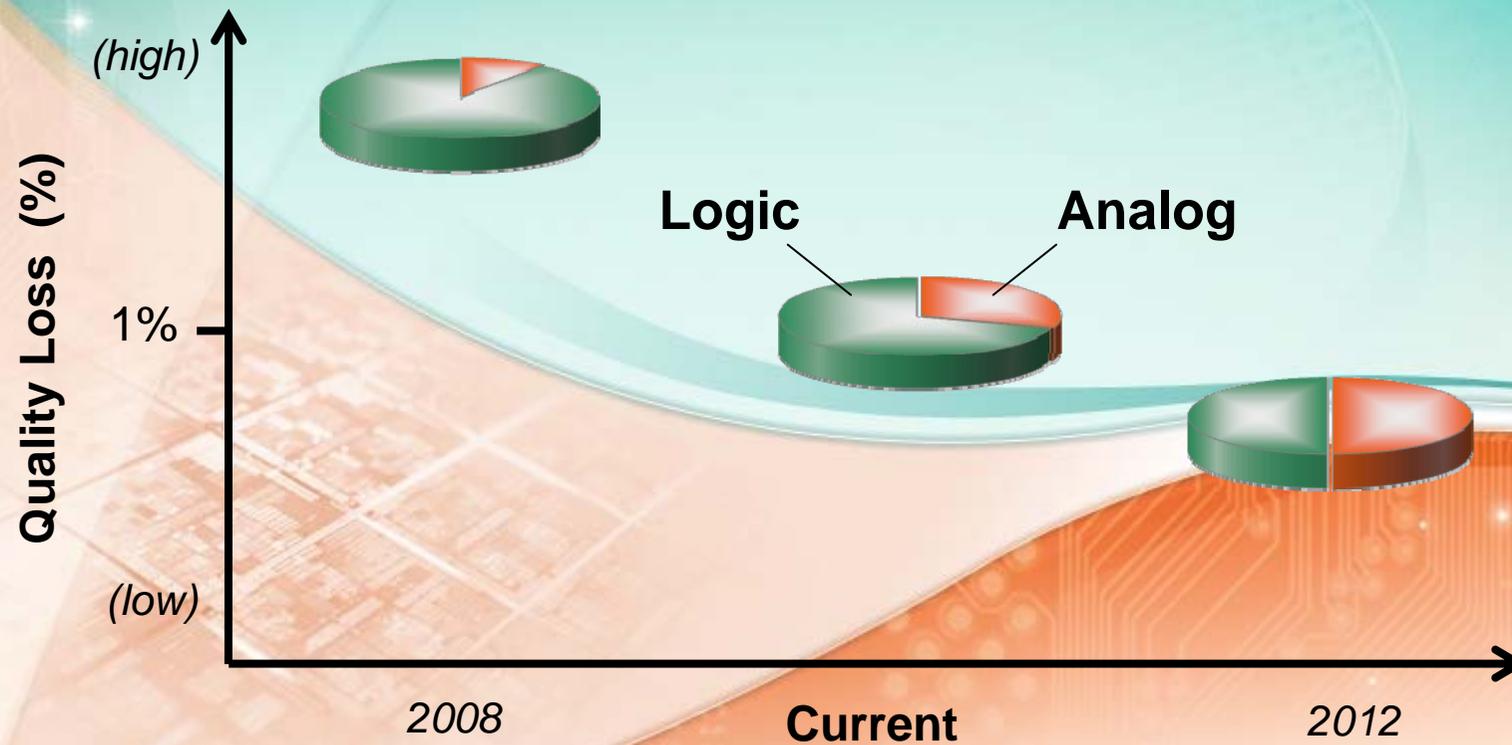
- ISO9001: 2000(update to ISO version 2000, Dec.09, 2003, BSI / IATF)
- ISO/TS16949 (Dec.09, 2003, BSI / IATF) for automotive

Certification in Environment Program

- ISO14001 (Jan.24, 2002, URS / UKAS)

Trend(3) Quality Loss Rate

- Reducing loss rate even higher analog volume



Technology Availability

● 90nm ~ 130nm
 ● 0.15 ~ 0.18μm
 ● 0.22 ~ 0.25μm
 ● 0.30 ~ 0.60μm

Process	Available Technology						
BCDMOS	● 0.35μm 1P3M 3.3V or 5V /8V, 12V ~ 60V	● 0.35μm 1P3M 3.3V or 5V /8V /85V	● 0.35μm 1P3M 5.5V, 7V ~ 24V	● 0.18μm 1P4M 1.8V/5V/12~60V			
Analog CMOS	● 0.6μm 1P3M 5V						
CIS	● 0.18μm 2.8um Pixel CIF, VGA,1.3M	● 0.13μm 2.2um Pixel VGA, 1.3M,2M	● 0.11μm 1.75μm Pixel 1.3M,2M				
RF	● 0.13μm 1P8M 1.2V/2.5&3.3V						
sFlash	● 0.18μm 2P3M 3.3V	● 0.13μm 2P3M 3.3V	● 0.13μm 2P3M 1.8V	● 90nm 2P3M 3.3V	● 90nm 2P3M 1.8V		
LDI	● 0.30μm 3.3/13.5V	● 0.18μm 3.3V/13.5V	● 0.18μm 3.3V/18V	● 0.16μm 1.8V/9V	● 0.16μm 1.8V/18V		
Standard Logic	● 0.30μm 1P4M 5V	● 0.25μm 1P5M 2.5V/3.3V	● 0.18μm 1P6M 1.8V/3.3V	● 0.18μm 1P6M 1.8V/5V	● 0.16/0.15μm 1P6M 1.8V/3.3V&5V	● 0.13μm 1P8M 1.2V/2.5&3.3V	● 0.11μm Cu/AL 1P6M 1.2V/3.3V
Low Power/Voltage	● 0.18μm 1P6M 1.5V/3.3V	● 0.18μm 1P6M 1.8V/2.5&3.3V	● 0.13μm 1P8M (Cu) 1.5V/2.5&3.3V				
Mixed Signal	● 0.25μm 1P5M 2.5V/3.3V	● 0.18μm 1P6M 1.8V/3.3V	● 0.18μm 1P6M 1.8V/3.3V&5V(Low Noise)	● 0.16μm 1P6M 1.8V/3.3V	● 0.15μm 1P6M 1.8V/3.3V	● 0.13μm 1P8M 1.2V/2.5&3.3V	

Conclusions

We are Committed to Your Success

- **Dongbu Hitek understands and is totally focused on the unique requirements of Analog Manufacturing.**
- **We have Invested in new and improved processes, capabilities and capacity till now.**
- **Our vision....To be “the Most Respected Analog Foundry in the Industry” !**

Thank You

